Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	PowerPC G2_LE
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	450MHz
Co-Processors/DSP	Communications; RISC CPM
RAM Controllers	DRAM, SDRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10/100Mbps (3)
SATA	-
USB	USB 2.0 (1)
Voltage - I/O	3.3V
Operating Temperature	-40°C ~ 105°C (TA)
Security Features	-
Package / Case	480-LBGA Exposed Pad
Supplier Device Package	480-TBGA (37.5x37.5)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mpc8270czuupea

1 Overview

This table shows the functionality supported by each SoC in the MPC8280 family.

Table 1. MPC8280 PowerQUICC II Family Functionality

| Functionality	Package[1]	SoCs			
		MPC8270		MPC8275	MPC8280
		480 TBGA	516 PBGA	516 PBGA	480 TBGA
Serial communications controllers (SCCs)		4	4	4	4
QUICC multi-channel controller (QMC)		—	—	—	—
Fast communication controllers (FCCs)		3	3	3	3
I-Cache (Kbyte)		16	16	16	16
D-Cache (Kbyte)		16	16	16	16
Ethernet (10/100)		3	3	3	3
UTOPIA II Ports		0	0	2	2
Multi-channel controllers (MCCs)		1	1	1	2
PCI bridge		Yes	Yes	Yes	Yes
Transmission convergence (TC) layer		—	—	—	Yes
Inverse multiplexing for ATM (IMA)		—	—	—	Yes
Universal serial bus (USB) 2.0 full/low rate		1	1	1	1
Security engine (SEC)		—	—	—	—

[1] See Table 2.

Devices in the MPC8280 family are available in four packages—the standard ZU and VV packages and the alternate VR or ZQ packages—as shown in Table 2. Note that throughout this document, references to the MPC8280 and the MPC8270 are inclusive of VR and ZQ package devices unless otherwise specified. For more information on VR and ZQ packages, contact your Freescale sales office. For package ordering information, see Section 10, "Ordering Information."

Table 2. HiP7 PowerQUICC II Device Packages

Code (Package)	ZU (480 TBGA—Leaded)	VV (480 TBGA—Lead Free)	VR (516 PBGA—Lead free)	ZQ (516 PBGA—Lead spheres)
Device	MPC8280	MPC8280	MPC8275VR	MPC8275ZQ
	MPC8270	MPC8270	MPC8270VR	MPC8270ZQ

This figure shows the block diagram of the SoC. Shaded portions are SoC-specific; see the notes below the figure.
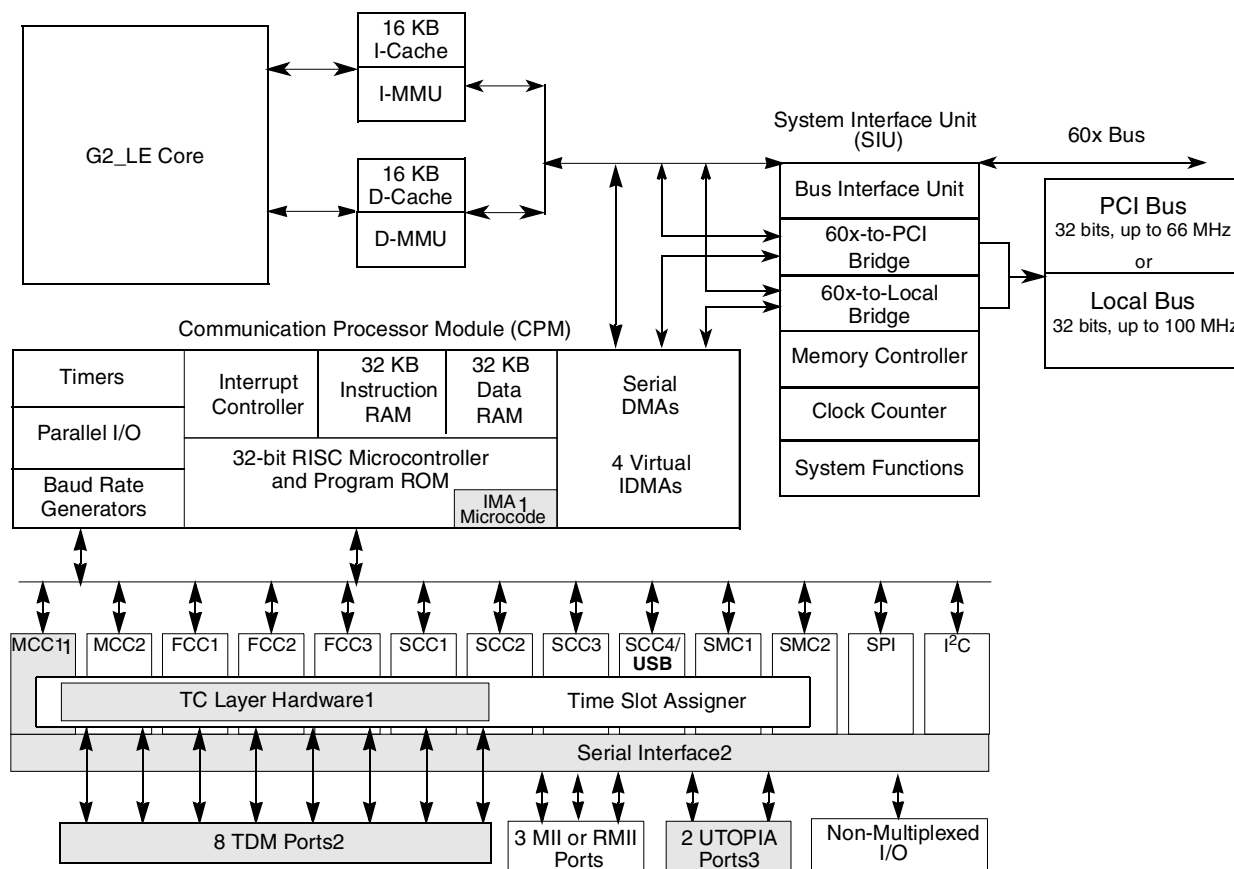
Notes:

[1] MPC8280 only (**not on MPC8270,** the VR package, nor the ZQ package)

[2] MPC8280 has 2 serial interface (SI) blocks and 8 TDM ports. MPC8270 and the VR and ZQ packages have only 1 SI block and 4 TDM ports (TDM2[A–D]).

[3] MPC8280, MPC8275VR, MPC8275ZQ only (**not on MPC8270,** MPC8270VR, nor MPC8270ZQ)

Figure 1. SoC Block Diagram

1.1   Features

The major features of the SoC are as follows:

- Dual-issue integer (G2_LE) core
  - A core version of the EC603e microprocessor
  - System core microprocessor supporting frequencies of 166–450 MHz
  - Separate 16 KB data and instruction caches:
    - Four-way set associative
    - Physically addressed
    - LRU replacement algorithm
  - Power Architecture®-compliant memory management unit (MMU)

- Provides management for BRI devices as general-circuit interface (GCI) controllers in time-division-multiplexed (TDM) channels
    - Transparent
    - UART (low-speed operation)
  — One serial peripheral interface identical to the MPC860 SPI
  — One I^2C controller (identical to the MPC860 I^2C controller)
    - Microwire compatible
    - Multiple-master, single-master, and slave modes
  — Up to eight TDM interfaces (four on the MPC8270)
    - Supports two groups of four TDM channels for a total of eight TDMs (one group of four on the MPC8270 and the MPC8275)
    - 2,048 bytes of SI RAM
    - Bit or byte resolution
    - Independent transmit and receive routing, frame synchronization
    - Supports T1, CEPT, T1/E1, T3/E3, pulse code modulation highway, ISDN basic rate, ISDN primary rate, Freescale interchip digital link (IDL), general circuit interface (GCI), and user-defined TDM serial interfaces
  — Eight independent baud rate generators and 20 input clock pins for supplying clocks to FCCs, SCCs, SMCs, and serial channels
  — Four independent 16-bit timers that can be interconnected as two 32-bit timers
- Inverse multiplexing for ATM capabilities (IMA) (MPC8280 only). Supported by eight transfer transmission convergence (TC) layers between the TDMs and FCC2.
- Transmission convergence (TC) layer (MPC8280 only)

2 Operating Conditions

This table shows the maximum electrical ratings.

Table 3. Absolute Maximum Ratings[1]

Rating	Symbol	Value	Unit
Core supply voltage[2]	VDD	−0.3 – 2.25	V
PLL supply voltage[2]	VCCSYN	−0.3 – 2.25	V
I/O supply voltage[3]	VDDH	−0.3 – 4.0	V
Input voltage[4]	VIN	GND(−0.3) – 3.6	V
Junction temperature	T_j	120	°C
Storage temperature range	T_{STG}	(−55) – (+150)	°C

[1] Absolute maximum ratings are stress ratings only; functional operation (see Table 4) at the maximums is not guaranteed. Stress beyond those listed may affect device reliability or cause permanent damage.

4.2 Estimation with Junction-to-Case Thermal Resistance

Historically, the thermal resistance has frequently been expressed as the sum of a junction-to-case thermal resistance and a case-to-ambient thermal resistance:

$$R_{\theta JA} = R_{\theta JC} + R_{\theta CA}$$

where:

$R_{\theta JA}$ = junction-to-ambient thermal resistance (ºC/W)

$R_{\theta JC}$ = junction-to-case thermal resistance (ºC/W)

$R_{\theta CA}$ = case-to-ambient thermal resistance (ºC/W)

$R_{\theta JC}$ is device related and cannot be influenced by the user. The user adjusts the thermal environment to affect the case-to-ambient thermal resistance, $R_{\theta CA}$. For instance, the user can change the air flow around the device, add a heat sink, change the mounting arrangement on the printed circuit board, or change the thermal dissipation on the printed circuit board surrounding the device. This thermal model is most useful for ceramic packages with heat sinks where some 90% of the heat flows through the case and the heat sink to the ambient environment. For most packages, a better model is required.

4.3 Estimation with Junction-to-Board Thermal Resistance

A simple package thermal model which has demonstrated reasonable accuracy (about 20%) is a two-resistor model consisting of a junction-to-board and a junction-to-case thermal resistance. The junction-to-case thermal resistance covers the situation where a heat sink is used or where a substantial amount of heat is dissipated from the top of the package. The junction-to-board thermal resistance describes the thermal performance when most of the heat is conducted to the printed circuit board. It has been observed that the thermal performance of most plastic packages, especially PBGA packages, is strongly dependent on the board temperature.

If the board temperature is known, an estimate of the junction temperature in the environment can be made using the following equation:

$$T_J = T_B + (R_{\theta JB} \times P_D)$$

where:

$R_{\theta JB}$ = junction-to-board thermal resistance (ºC/W)

T_B = board temperature (ºC)

P_D = power dissipation in package

If the board temperature is known and the heat loss from the package case to the air can be ignored, acceptable predictions of junction temperature can be made. For this method to work, the board and board mounting must be similar to the test board used to determine the junction-to-board thermal resistance, namely a 2s2p (board with a power and a ground plane) and by attaching the thermal balls to the ground plane.

4.4 Estimation Using Simulation

When the board temperature is not known, a thermal simulation of the application is needed. The simple two-resistor model can be used with the thermal simulation of the application, or a more accurate and complex model of the package can be used in the thermal simulation.

4.5 Experimental Determination

To determine the junction temperature of the device in the application after prototypes are available, the thermal characterization parameter (Ψ_{JT}) can be used to determine the junction temperature with a measurement of the temperature at the top center of the package case using the following equation:

$$T_J = T_T + (\Psi_{JT} \times P_D)$$

where:

Ψ_{JT} = thermal characterization parameter

T_T = thermocouple temperature on top of package

P_D = power dissipation in package

The thermal characterization parameter is measured per JEDEC JESD51-2 specification using a 40-gauge type T thermocouple epoxied to the top center of the package case. The thermocouple should be positioned so that the thermocouple junction rests on the package. A small amount of epoxy is placed over the thermocouple junction and over 1 mm of wire extending from the junction. The thermocouple wire is placed flat against the case to avoid measurement errors caused by cooling effects of the thermocouple wire.

4.6 Layout Practices

Each VDD and VDDH pin should be provided with a low-impedance path to the board's power supplies. Each ground pin should likewise be provided with a low-impedance path to ground. The power supply pins drive distinct groups of logic on chip. The VDD and VDDH power supplies should be bypassed to ground using bypass capacitors located as close as possible to the four sides of the package. For filtering high frequency noise, a capacitor of 0.1uF on each VDD and VDDH pin is recommended. Further, for medium frequency noise, a total of 2 capacitors of 47uF for VDD and 2 capacitors of 47uF for VDDH are also recommended. The capacitor leads and associated printed circuit traces connecting to chip VDD, VDDH and ground should be kept to less than half an inch per capacitor lead. Boards should employ separate inner layers for power and GND planes.

All output pins on the SoC have fast rise and fall times. Printed circuit (PC) trace interconnection length should be minimized to minimize overdamped conditions and reflections caused by these fast output switching times. This recommendation particularly applies to the address and data buses. Maximum PC trace lengths of six inches are recommended. Capacitance calculations should consider all device loads as well as parasitic capacitances due to the PC traces. Attention to proper PCB layout and bypassing becomes especially critical in systems with higher capacitive loads because these loads create higher transient currents in the VDD and GND circuits. Pull up all unused inputs or signals that will be inputs during reset. Special care should be taken to minimize the noise levels on the PLL supply pins.

This figure shows the FCC external clock.
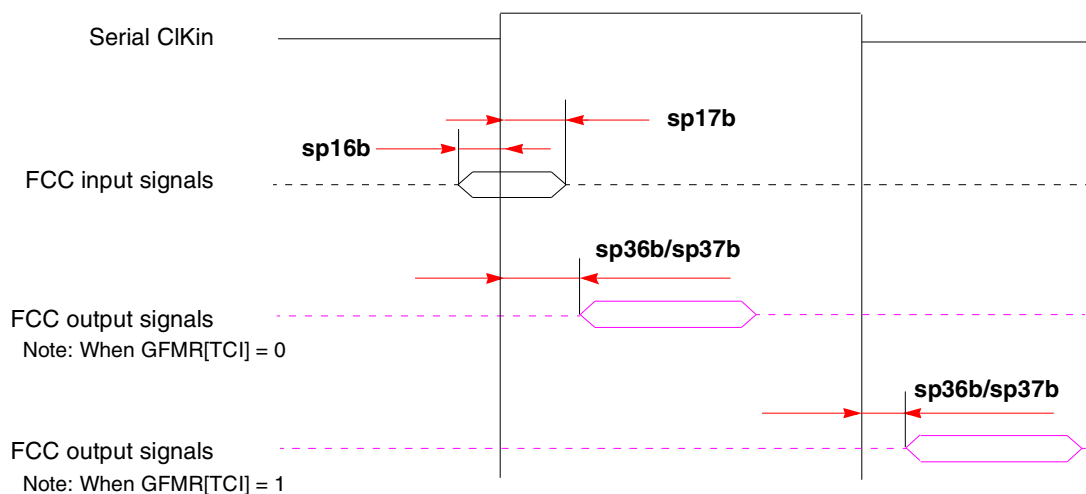
Figure 4. FCC External Clock Diagram

This figure shows the SCC/SMC/SPI/I^{2}C external clock.
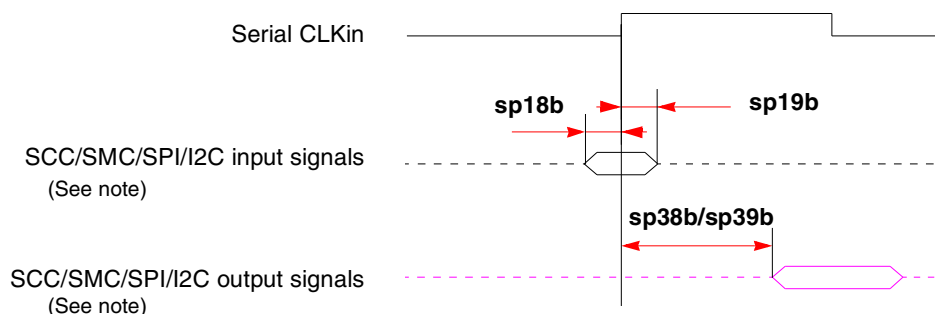
Note: There are four possible timing conditions for SCC and SPI:
1. Input sampled on the rising edge and output driven on the rising edge (shown).
2. Input sampled on the rising edge and output driven on the falling edge.
3. Input sampled on the falling edge and output driven on the falling edge.
4. Input sampled on the falling edge and output driven on the rising edge.

Figure 5. SCC/SMC/SPI/I^{2}C External Clock Diagram

This figure shows the interaction of several bus signals.

Figure 9. Bus Signals

Table 19. Clock Configurations for PCI Host Mode (PCI_MODCK=0)[1,2] (continued)

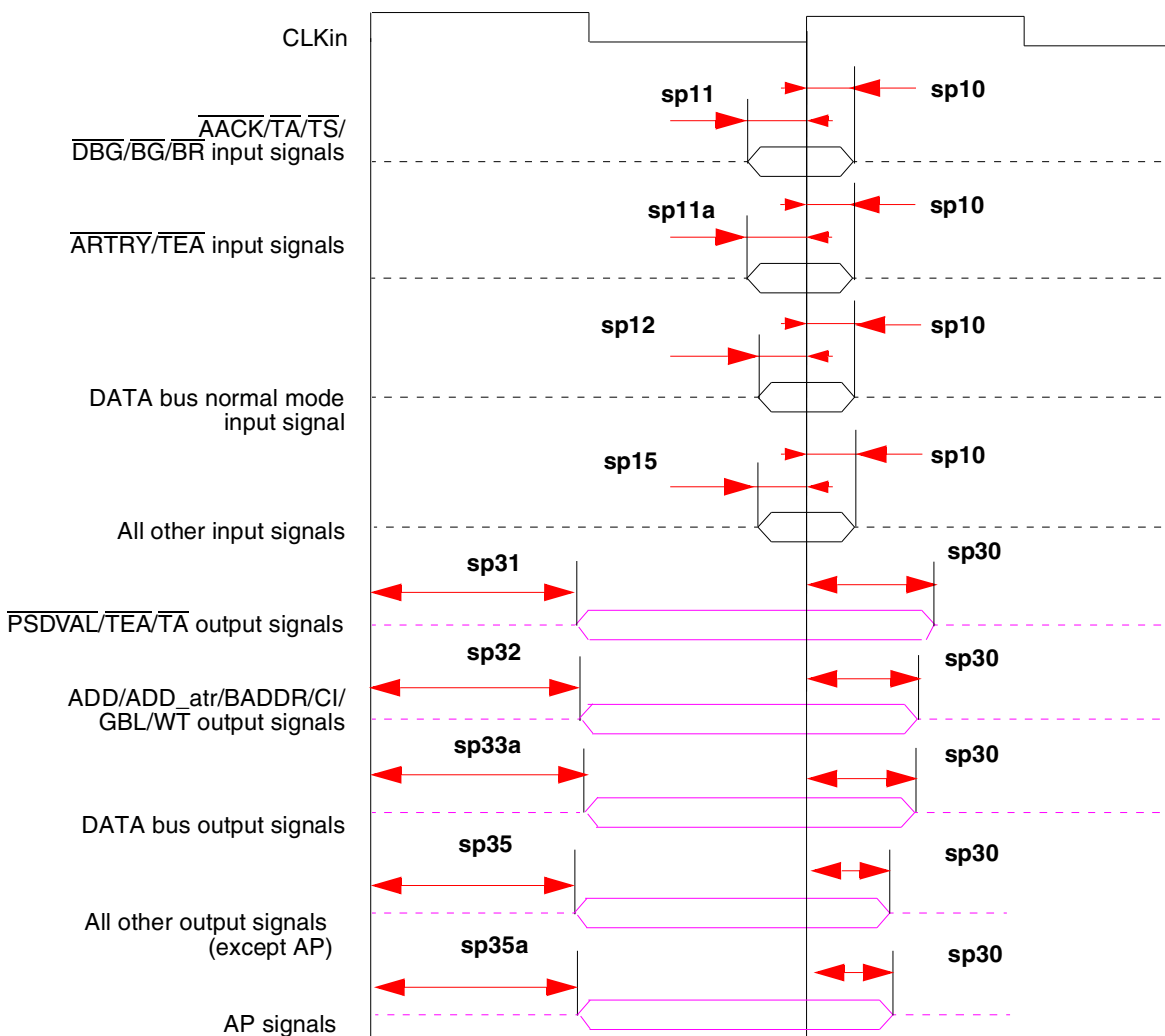| Mode[3] MODCK_H-MODCK[1-3]	Bus Clock[4] (MHz)		CPM Multiplication Factor[5]	CPM Clock (MHz)		CPU Multiplication Factor[6]	CPU Clock (MHz)		PCI Division Factor	PCI Clock (MHz)	
	Low	High		Low	High		Low	High		Low	High
0001_001	50.0	66.7	3	150.0	200.0	6	300.0	400.0	3	50.0	66.7
0001_010	50.0	66.7	3	150.0	200.0	7	350.0	466.6	3	50.0	66.7
0001_011	50.0	66.7	3	150.0	200.0	8	400.0	533.3	3	50.0	66.7
0010_000	50.0	66.7	4	200.0	266.6	5	250.0	333.3	4	50.0	66.7
0010_001	50.0	66.7	4	200.0	266.6	6	300.0	400.0	4	50.0	66.7
0010_010	50.0	66.7	4	200.0	266.6	7	350.0	466.6	4	50.0	66.7
0010_011	50.0	66.7	4	200.0	266.6	8	400.0	533.3	4	50.0	66.7
0010_100	75.0	100.0	4	300.0	400.0	5	375.0	500.0	6	50.0	66.7
0010_101	75.0	100.0	4	300.0	400.0	5.5	412.5	549.9	6	50.0	66.7
0010_110	75.0	100.0	4	300.0	400.0	6	450.0	599.9	6	50.0	66.7
0011_000	50.0	66.7	5	250.0	333.3	5	250.0	333.3	5	50.0	66.7
0011_001	50.0	66.7	5	250.0	333.3	6	300.0	400.0	5	50.0	66.7
0011_010	50.0	66.7	5	250.0	333.3	7	350.0	466.6	5	50.0	66.7
0011_011	50.0	66.7	5	250.0	333.3	8	400.0	533.3	5	50.0	66.7
0100_000	Reserved										
0100_001	50.0	66.7	6	300.0	400.0	6	300.0	400.0	6	50.0	66.7
0100_010	50.0	66.7	6	300.0	400.0	7	350.0	466.6	6	50.0	66.7
0100_011	50.0	66.7	6	300.0	400.0	8	400.0	533.3	6	50.0	66.7
0101_000	60.0	66.7	2	120.0	133.3	2.5	150.0	166.7	2	60.0	66.7
0101_001	50.0	66.7	2	100.0	133.3	3	150.0	200.0	2	50.0	66.7
0101_010	50.0	66.7	2	100.0	133.3	3.5	175.0	233.3	2	50.0	66.7
0101_011	50.0	66.7	2	100.0	133.3	4	200.0	266.6	2	50.0	66.7
0101_100	50.0	66.7	2	100.0	133.3	4.5	225.0	300.0	2	50.0	66.7
0110_000	60.0	80.0	2.5	150.0	200.0	2.5	150.0	200.0	3	50.0	66.7
0110_001	60.0	80.0	2.5	150.0	200.0	3	180.0	240.0	3	50.0	66.7
0110_010	60.0	80.0	2.5	150.0	200.0	3.5	210.0	280.0	3	50.0	66.7

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Table 20. Clock Configurations for PCI Host Mode (PCI_MODCK=1)[1,2] (continued)

Mode[3]	Bus Clock[4] (MHz)		CPM Multiplication Factor[5]	CPM Clock (MHz)		CPU Multiplication Factor[6]	CPU Clock (MHz)		PCI Division Factor	PCI Clock (MHz)	
MODCK_H-MODCK[1-3]	Low	High		Low	High		Low	High		Low	High
1000_000	Reserved										
1000_001	66.7	133.3	3	200.0	400.0	3	200.0	400.0	8	25.0	50.0
1000_010	66.7	133.3	3	200.0	400.0	3.5	233.3	466.7	8	25.0	50.0
1000_011	66.7	133.3	3	200.0	400.0	4	266.7	533.3	8	25.0	50.0
1000_100	66.7	133.3	3	200.0	400.0	4.5	300.0	600.0	8	25.0	50.0
1000_101	66.7	133.3	3	200.0	400.0	6	400.0	800.0	8	25.0	50.0
1000_110	66.7	133.3	3	200.0	400.0	6.5	433.3	866.7	8	25.0	50.0
1001_000	Reserved										
1001_001	Reserved										
1001_010	57.1	114.3	3.5	200.0	400.0	3.5	200.0	400.0	8	25.0	50.0
1001_011	57.1	114.3	3.5	200.0	400.0	4	228.6	457.1	8	25.0	50.0
1001_100	57.1	114.3	3.5	200.0	400.0	4.5	257.1	514.3	8	25.0	50.0
1001_101	42.9	85.7	3.5	150.0	300.0	5	214.3	428.6	6	25.0	50.0
1001_110	42.9	85.7	3.5	150.0	300.0	5.5	235.7	471.4	6	25.0	50.0
1001_111	42.9	85.7	3.5	150.0	300.0	6	257.1	514.3	6	25.0	50.0
1010_000	75.0	150.0	2	150.0	300.0	2	150.0	300.0	6	25.0	50.0
1010_001	75.0	150.0	2	150.0	300.0	2.5	187.5	375.0	6	25.0	50.0
1010_010	75.0	150.0	2	150.0	300.0	3	225.0	450.0	6	25.0	50.0
1010_011	75.0	150.0	2	150.0	300.0	3.5	262.5	525.0	6	25.0	50.0
1010_100	75.0	150.0	2	150.0	300.0	4	300.0	600.0	6	25.0	50.0
1011_000	Reserved										
1011_001	80.0	160.0	2.5	200.0	400.0	2.5	200.0	400.0	8	25.0	50.0
1011_010	80.0	160.0	2.5	200.0	400.0	3	240.0	480.0	8	25.0	50.0
1011_011	80.0	160.0	2.5	200.0	400.0	3.5	280.0	560.0	8	25.0	50.0
1011_100	80.0	160.0	2.5	200.0	400.0	4	320.0	640.0	8	25.0	50.0
1011_101	80.0	160.0	2.5	200.0	400.0	4.5	360.0	720.0	8	25.0	50.0
1101_000	50.0	100.0	2.5	125.0	250.0	3	150.0	300.0	5	25.0	50.0

Table 21. Clock Configurations for PCI Agent Mode (PCI_MODCK=0)[1,2] (continued)

Mode[3]	PCI Clock (MHz)		CPM Multiplication Factor[4]	CPM Clock (MHz)		CPU Multiplication Factor[5]	CPU Clock (MHz)		Bus Division Factor	Bus Clock (MHz)	
MODCK_H-MODCK[1-3]	Low	High		Low	High		Low	High		Low	High
0100_000	Reserved										
0100_001	50.0	66.7	3	150.0	200.0	3	150.0	200.0	3	50.0	66.7
0100_010	50.0	66.7	3	150.0	200.0	3.5	175.0	200.0	3	50.0	66.7
0100_011	50.0	66.7	3	150.0	200.0	4	200.0	266.6	3	50.0	66.7
0100_100	50.0	66.7	3	150.0	200.0	4.5	225.0	300.0	3	50.0	66.7
0101_000	50.0	66.7	5	250.0	333.3	2.5	250.0	333.3	2.5	100.0	133.3
0101_001	50.0	66.7	5	250.0	333.3	3	300.0	400.0	2.5	100.0	133.3
0101_010	50.0	66.7	5	250.0	333.3	3.5	350.0	466.6	2.5	100.0	133.3
0101_011	50.0	66.7	5	250.0	333.3	4	400.0	533.3	2.5	100.0	133.3
0101_100	50.0	66.7	5	250.0	333.3	4.5	450.0	599.9	2.5	100.0	133.3
0101_101	50.0	66.7	5	250.0	333.3	5	500.0	666.6	2.5	100.0	133.3
0101_110	50.0	66.7	5	250.0	333.3	5.5	550.0	733.3	2.5	100.0	133.3
0110_000	Reserved										
0110_001	50.0	66.7	4	200.0	266.6	3	200.0	266.6	3	66.7	88.9
0110_010	50.0	66.7	4	200.0	266.6	3.5	233.3	311.1	3	66.7	88.9
0110_011	50.0	66.7	4	200.0	266.6	4	266.7	355.5	3	66.7	88.9
0110_100	50.0	66.7	4	200.0	266.6	4.5	300.0	400.0	3	66.7	88.9
0111_000	50.0	66.7	3	150.0	200.0	2	150.0	200.0	2	75.0	100.0
0111_001	50.0	66.7	3	150.0	200.0	2.5	187.5	250.0	2	75.0	100.0
0111_010	50.0	66.7	3	150.0	200.0	3	225.0	300.0	2	75.0	100.0
0111_011	50.0	66.7	3	150.0	200.0	3.5	262.5	350.0	2	75.0	100.0
1000_000	Reserved										
1000_001	50.0	66.7	3	150.0	200.0	2.5	150.0	166.7	2.5	60.0	80.0
1000_010	50.0	66.7	3	150.0	200.0	3	180.0	240.0	2.5	60.0	80.0
1000_011	50.0	66.7	3	150.0	200.0	3.5	210.0	280.0	2.5	60.0	80.0
1000_100	50.0	66.7	3	150.0	200.0	4	240.0	320.0	2.5	60.0	80.0
1000_101	50.0	66.7	3	150.0	200.0	4.5	270.0	360.0	2.5	60.0	80.0

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Table 22. Clock Configurations for PCI Agent Mode (PCI_MODCK=1)[1,2] (continued)

Mode[3]	PCI Clock (MHz)		CPM Multiplication Factor[4]	CPM Clock (MHz)		CPU Multiplication Factor[5]	CPU Clock (MHz)		Bus Division Factor	Bus Clock (MHz)	
MODCK_H-MODCK[1-3]	Low	High		Low	High		Low	High		Low	High
1011_010	25.0	50.0	8	200.0	400.0	3	240.0	480.0	2.5	80.0	160.0
1011_011	25.0	50.0	8	200.0	400.0	3.5	280.0	560.0	2.5	80.0	160.0
1011_100	25.0	50.0	8	200.0	400.0	4	320.0	640.0	2.5	80.0	160.0
1100_101	25.0	50.0	6	150.0	300.0	4	200.0	400.0	3	50.0	100.0
1100_110	25.0	50.0	6	150.0	300.0	4.5	225.0	450.0	3	50.0	100.0
1100_111	25.0	50.0	6	150.0	300.0	5	250.0	500.0	3	50.0	100.0
1101_000	25.0	50.0	6	150.0	300.0	5.5	275.0	550.0	3	50.0	100.0
1101_001	25.0	50.0	6	150.0	300.0	3.5	210.0	420.0	2.5	60.0	120.0
1101_010	25.0	50.0	6	150.0	300.0	4	240.0	480.0	2.5	60.0	120.0
1101_011	25.0	50.0	6	150.0	300.0	4.5	270.0	540.0	2.5	60.0	120.0
1101_100	25.0	50.0	6	150.0	300.0	5	300.0	600.0	2.5	60.0	120.0
1110_000	25.0	50.0	5	125.0	250.0	2.5	156.3	312.5	2	62.5	125.0
1110_001	25.0	50.0	5	125.0	250.0	3	187.5	375.0	2	62.5	125.0
1110_010	25.0	50.0	5	125.0	250.0	3.5	218.8	437.5	2	62.5	125.0
1110_011	25.0	50.0	5	125.0	250.0	4	250.0	500.0	2	62.5	125.0
1110_100	25.0	50.0	5	125.0	250.0	4	166.7	333.3	3	41.7	83.3
1110_101	25.0	50.0	5	125.0	250.0	4.5	187.5	375.0	3	41.7	83.3
1110_110	25.0	50.0	5	125.0	250.0	5	208.3	416.7	3	41.7	83.3
1110_111	25.0	50.0	5	125.0	250.0	5.5	229.2	458.3	3	41.7	83.3
1100_000	Reserved										
1100_001	Reserved										
1100_010	Reserved										

[1] The "low" values are the minimum allowable frequencies for a given clock mode. The minimum bus frequency in a table entry guarantees only the required minimum CPU operating frequency. The "high" values are for the purpose of illustration only. Users must select a mode and input bus frequency so that the resulting configuration does not violate the frequency rating of the user's device. The minimum CPM frequency is 120 MHz. Minimum CPU frequency is determined by the clock mode. For modes with a CPU multiplication factor <= 3, the minimum CPU frequency is 150 MHz for commercial temperature devices and 175 MHz for extended temperature devices. For modes with a CPU multiplication factor >= 3.5: for Rev 0.1 the minimum CPU frequency is 250 MHz; for Rev A or later the minimum CPU frequency is 150 MHz for commercial temperature devices and 175 MHz for extended temperature devices.

Table 23. MPC8280 and MPC8270 (ZU and VV Packages) Pinout List (continued)

Pin Name		Ball
MPC8280/MPC8270	**MPC8280 only**	
D18		D15
D19		C13
D20		B11
D21		A8
D22		A5
D23		C5
D24		C19
D25		C17
D26		C15
D27		D13
D28		C11
D29		B8
D30		A4
D31		E6
D32		E18
D33		B17
D34		A15
D35		A12
D36		D11
D37		C8
D38		E7
D39		A3
D40		D18
D41		A17
D42		A14
D43		B12
D44		A10
D45		D8
D46		B6
D47		C4
D48		C18
D49		E16
D50		B14

Table 23. MPC8280 and MPC8270 (ZU and VV Packages) Pinout List (continued)

Pin Name		Ball
MPC8280/MPC8270	**MPC8280 only**	
$\overline{CS2}$		E27
$\overline{CS3}$		E28
$\overline{CS4}$		F26
$\overline{CS5}$		F27
$\overline{CS6}$		F28
$\overline{CS7}$		G25
$\overline{CS8}$		D29
$\overline{CS9}$		E29
$\overline{CS10}$/$\overline{BCTL1}$		F29
$\overline{CS11}$/AP0		G28
BADDR27		T5
BADDR28		U1
ALE		T2
$\overline{BCTL0}$		A27
$\overline{PWE0}$/$\overline{PSDDQM0}$/$\overline{PBS0}$		C25
$\overline{PWE1}$/$\overline{PSDDQM1}$/$\overline{PBS1}$		E24
$\overline{PWE2}$/$\overline{PSDDQM2}$/$\overline{PBS2}$		D24
$\overline{PWE3}$/$\overline{PSDDQM3}$/$\overline{PBS3}$		C24
$\overline{PWE4}$/$\overline{PSDDQM4}$/$\overline{PBS4}$		B26
$\overline{PWE5}$/$\overline{PSDDQM5}$/$\overline{PBS5}$		A26
$\overline{PWE6}$/$\overline{PSDDQM6}$/$\overline{PBS6}$		B25
$\overline{PWE7}$/$\overline{PSDDQM7}$/$\overline{PBS7}$		A25
PSDA10/PGPL0		E23
$\overline{PSDWE}$/PGPL1		B24
$\overline{POE}$/$\overline{PSDRAS}$/PGPL2		A24
$\overline{PSDCAS}$/PGPL3		B23
$\overline{PGTA}$/PUPMWAIT/PGPL4/$\overline{PPBS}$		A23
PSDAMUX/PGPL5		D22
$\overline{LWE0}$/$\overline{LSDDQM0}$/$\overline{LBS0}$/PCI_CFG0		H28
$\overline{LWE1}$/$\overline{LSDDQM1}$/$\overline{LBS1}$/PCI_CFG1		H27
$\overline{LWE2}$/$\overline{LSDDQM2}$/$\overline{LBS2}$/PCI_CFG2		H26
$\overline{LWE3}$/$\overline{LSDDQM3}$/$\overline{LBS3}$/PCI_CFG3		G29
LSDA10/LGPL0/PCI_MODCKH0		D27

This figure shows the pinout of the VR and ZQ packages as viewed from the top surface.
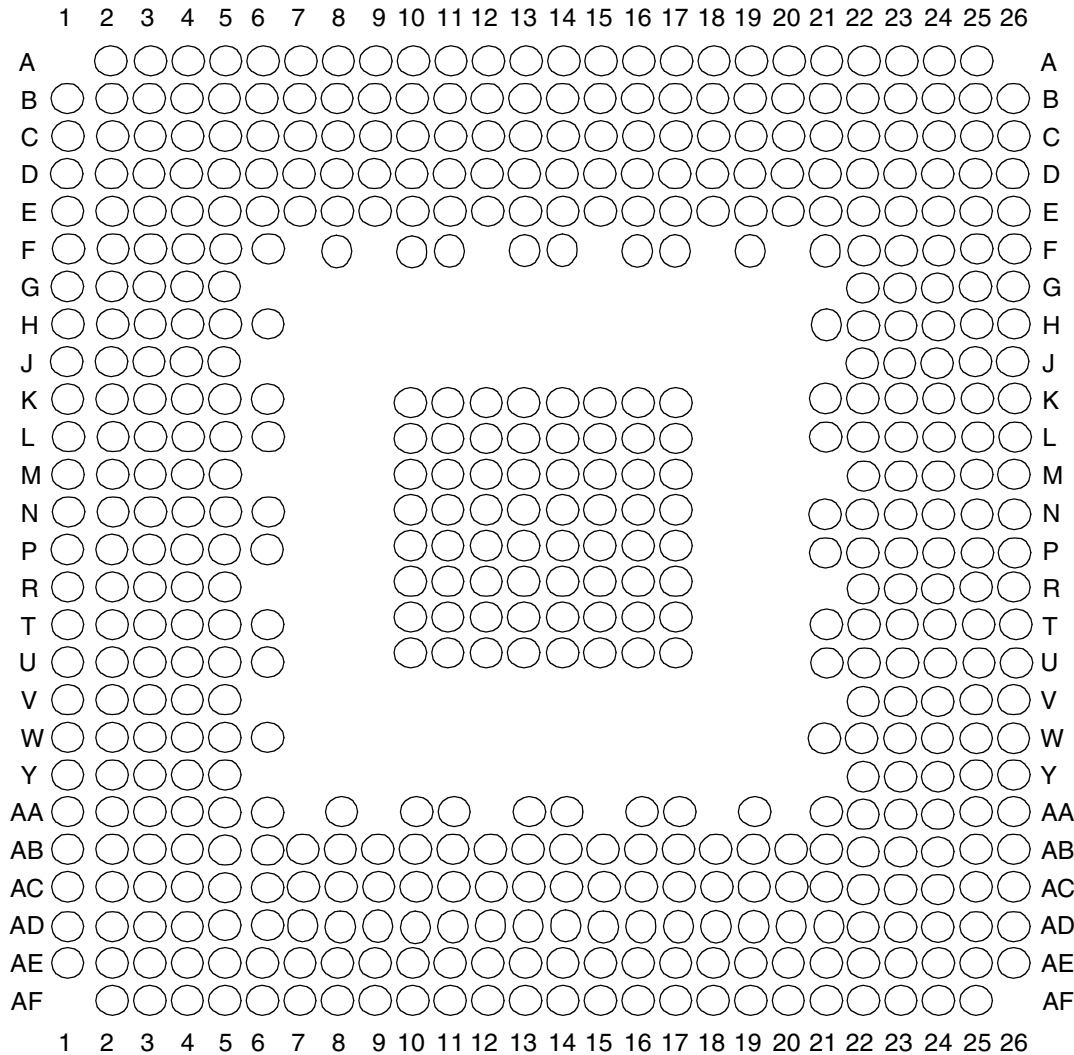
Not to Scale

Figure 14. Pinout of the 516 PBGA Package (View from Top)

This table shows the pinout list of the MPC8275 and MPC8270. Table 24 defines conventions and acronyms used in Table 25.

Table 25. MPC8275 and MPC8270 (VR and ZQ Packages) Pinout List

Pin Name		Ball
MPC8275/MPC8270	**MPC8275 only**	
$\overline{BR}$		C16
$\overline{BG}$		D2
$\overline{ABB}/\overline{IRQ2}$		C1
$\overline{TS}$		D1

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Table 25. MPC8275 and MPC8270 (VR and ZQ Packages) Pinout List (continued)

Pin Name		Ball
MPC8275/MPC8270	**MPC8275 only**	
D53		J2
D54		H5
D55		F3
D56		V3
D57		R5
D58		R2
D59		N5
D60		L2
D61		J3
D62		H1
D63		F4
DP0/$\overline{\text{RSRV}}$/$\overline{\text{EXT\_BR2}}$		AB3
$\overline{\text{IRQ1}}$/DP1/$\overline{\text{EXT\_BG2}}$		W5
$\overline{\text{IRQ2}}$/DP2/TLBISYNC/$\overline{\text{EXT\_DBG2}}$		AC2
$\overline{\text{IRQ3}}$/DP3/$\overline{\text{CKSTP\_OUT}}$/$\overline{\text{EXT\_BR3}}$		AA3
$\overline{\text{IRQ4}}$/DP4/$\overline{\text{CORE\_SRESET}}$/$\overline{\text{EXT\_BG3}}$		AD1
$\overline{\text{IRQ5}}$/$\overline{\text{CINT}}$/DP5/$\overline{\text{TBEN}}$/$\overline{\text{EXT\_DBG3}}$		AC1
$\overline{\text{IRQ6}}$/DP6/$\overline{\text{CSE0}}$		AB2
$\overline{\text{IRQ7}}$/DP7/$\overline{\text{CSE1}}$		Y3
$\overline{\text{PSDVAL}}$		D15
$\overline{\text{TA}}$		Y4
$\overline{\text{TEA}}$		D16
$\overline{\text{GBL}}$/$\overline{\text{IRQ1}}$		E15
$\overline{\text{CI}}$/BADDR29/$\overline{\text{IRQ2}}$		D14
$\overline{\text{WT}}$/BADDR30/$\overline{\text{IRQ3}}$		E14
L2_HIT/$\overline{\text{IRQ4}}$		A17
$\overline{\text{CPU\_BG}}$/BADDR31/$\overline{\text{IRQ5}}$/$\overline{\text{CINT}}$		B14
$\overline{\text{CPU\_DBG}}$		F13
$\overline{\text{CPU\_BR}}$		B17
$\overline{\text{CS0}}$		AC6
$\overline{\text{CS1}}$		AD6
$\overline{\text{CS2}}$		AE6
$\overline{\text{CS3}}$		AB7

Table 25. MPC8275 and MPC8270 (VR and ZQ Packages) Pinout List (continued)

Pin Name		Ball
MPC8275/MPC8270	**MPC8275 only**	**Ball**
$\overline{CS4}$		AF7
$\overline{CS5}$		AC7
$\overline{CS6}$		AD7
$\overline{CS7}$		AF8
$\overline{CS8}$		AE8
$\overline{CS9}$		AD8
$\overline{CS10}/\overline{BCTL1}$		AC8
$\overline{CS11}/AP0$		AB8
BADDR27		C13
BADDR28		A12
ALE		D13
$\overline{BCTL0}$		AF4
$\overline{PWE0}/\overline{PSDDQM0}/\overline{PBS0}$		AA5
$\overline{PWE1}/\overline{PSDDQM1}/\overline{PBS1}$		AE4
$\overline{PWE2}/\overline{PSDDQM2}/\overline{PBS2}$		AD4
$\overline{PWE3}/\overline{PSDDQM3}/\overline{PBS3}$		AF3
$\overline{PWE4}/\overline{PSDDQM4}/\overline{PBS4}$		AB4
$\overline{PWE5}/\overline{PSDDQM5}/\overline{PBS5}$		AE3
$\overline{PWE6}/\overline{PSDDQM6}/\overline{PBS6}$		AF2
$\overline{PWE7}/\overline{PSDDQM7}/\overline{PBS7}$		AD3
PSDA10/PGPL0		AE2
$\overline{PSDWE}/PGPL1$		AD2
$\overline{POE}/\overline{PSDRAS}/PGPL2$		AE1
$\overline{PSDCAS}/PGPL3$		AC3
$\overline{PGTA}/\overline{PUPMWAIT}/PGPL4/\overline{PPBS}$		W6
PSDAMUX/PGPL5		AA4
$\overline{LWE0}/\overline{LSDDQM0}/\overline{LBS0}/PCI\_CFG0$		AC9
$\overline{LWE1}/\overline{LSDDQM1}/\overline{LBS1}/PCI\_CFG1$		AD9
$\overline{LWE2}/\overline{LSDDQM2}/\overline{LBS2}/PCI\_CFG2$		AE9
$\overline{LWE3}/\overline{LSDDQM3}/\overline{LBS3}/PCI\_CFG3$		AF9
LSDA10/LGPL0/PCI_MODCKH0		AB6
$\overline{LSDWE}/LGPL1/PCI\_MODCKH1$		AF5
$\overline{LOE}/\overline{LSDRAS}/LGPL2/PCI\_MODCKH2$		AE5

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Table 25. MPC8275 and MPC8270 (VR and ZQ Packages) Pinout List (continued)

Pin Name		Ball
MPC8275/MPC8270	**MPC8275 only**	
PA19/FCC1_MII_HDLC_TXD1/ FCC1_RMII_TXD1	FCC1_UT8_TXD6/FCC1_UT16_TXD14	N23[2]
PA20/FCC1_MII_HDLC_TXD2	FCC1_UT8_TXD5/FCC1_UT16_TXD13	K26[2]
PA21/FCC1_MII_HDLC_TXD3	FCC1_UT8_TXD4/FCC1_UT16_TXD12	L23[2]
PA22	FCC1_UT8_TXD3/FCC1_UT16_TXD11	K23[2]
PA23	FCC1_UT8_TXD2/FCC1_UT16_TXD10	H26[2]
PA24/MSNUM1	FCC1_UT8_TXD1/FCC1_UT16_TXD9	F25[2]
PA25/MSNUM0	FCC1_UT8_TXD0/FCC1_UT16_TXD8	D26[2]
PA26/FCC1_MII_RMII_RX_ER/	FCC1_UTM_RXCLAV/ FCC1_UTS_RXCLAV	D25[2]
PA27/FCC1_MII_RX_DV/ FCC1_RMII_CRS_DV	FCC1_UT_RXSOC	C25[2]
PA28/FCC1_MII_TX_EN/ FCC1_RMII_TX_EN	FCC1_UTM_RXENB/ FCC1_UTS_RXENB	C22[2]
PA29/FCC1_MII_TX_ER	FCC1_UT_TXSOC	B21[2]
PA30/FCC1_MII_CRS/FCC1_RTS	FCC1_UTM_TXCLAV/ FCC1_UTS_TXCLAV	A20[2]
PA31/FCC1_MII_COL	FCC1_UTM_TXENB/ FCC1_UTS_TXENB	A19[2]
PB4/FCC3_MII_HDLC_TXD3/ L1RSYNCA2/FCC3_RTS	FCC2_UT8_RXD0	AD21[2]
PB5/FCC3_MII_HDLC_TXD2/ L1TSYNCA2/L1GNTA2	FCC2_UT8_RXD1	AD22[2]
PB6/FCC3_MII_HDLC_TXD1/ FCC3_RMII_TXD1/ L1RXDA2/L1RXD0A2	FCC2_UT8_RXD2	AC22[2]
PB7/FCC3_MII_HDLC_TXD0/ FCC3_RMII_TXD0/ FCC3_TXD/L1TXDA2/L1TXD0A2	FCC2_UT8_RXD3	AE26[2]
PB8/FCC3_MII_HDLC_RXD0/ FCC3_RMII_RXD0/ FCC3_RXD/TXD3	FCC2_UT8_TXD3	AB23[2]
PB9/FCC3_MII_HDLC_RXD1/ FCC3_RMII_RXD1/L1TXD2A2	FCC2_UT8_TXD2	AC26[2]
PB10/FCC3_MII_HDLC_RXD2	FCC2_UT8_TXD1	AB26[2]
PB11/FCC3_MII_HDLC_RXD3	FCC2_UT8_TXD0	AA25[2]
PB12/FCC3_MII_CRS/TXD2		W26[2]
PB13/FCC3_MII_COL/L1TXD1A2		W25[2]
PB14/FCC3_MII_RMII_TX_EN/RXD3		V24[2]

Table 25. MPC8275 and MPC8270 (VR and ZQ Packages) Pinout List (continued)

Pin Name		Ball
MPC8275/MPC8270	**MPC8275 only**	
PB15/FCC3_MII_TX_ER/RXD2		U24[2]
PB16/FCC3_MII_RMII_RX_ER/CLK18		R22[2]
PB17/FCC3_MII_RX_DV/CLK17/ FCC3_RMII_CRS_DV		R23[2]
PB18/FCC2_MII_HDLC_RXD3/ L1CLKOD2/L1RXD2A2	FCC2_UT8_RXD4	M23[2]
PB19FCC2_MII_HDLC_RXD2/ L1RQD2/L1RXD3A2	FCC2_UT8_RXD5	L24[2]
PB20/FCC2_MII_HDLC_RMII_RXD1/ L1RSYNCD2	FCC2_UT8_RXD6	K24[2]
PB21//FCC2_MII_HDLC_RMII_RXD0/ FCC2_TRAN_RXD/L1TSYNCD2/ L1GNTD2	FCC2_UT8_RXD7	L21[2]
PB22/FCC2_MII_HDLC_RMII_TXD0/ FCC2_TXD/FCC2_RMII_TXD0/ L1RXDD2	FCC2_UT8_TXD7	P25[2]
PB23/FCC2_MII_HDLC_TXD1/ L1RXD2A1/L1TXDD2/ FCC2_RMII_TXD1	FCC2_UT8_TXD6	N25[2]
PB24/FCC2_MII_HDLC_TXD2/ L1RSYNCC2	FCC2_UT8_TXD5	E26[2]
PB25/FCC2_MII_HDLC_TXD3/ L1TSYNCC2/L1GNTC2	FCC2_UT8_TXD4	H23[2]
PB26/FCC2_MII_CRS/L1RXDC2	FCC2_UT8_TXD1	C26[2]
PB27/FCC2_MII_COL/L1TXDC2	FCC2_UT8_TXD0	B26[2]
PB28/FCC2_MII_RX_ER/FCC2_RMII_RX_ER/ $\overline{FCC2\_RTS}$/L1TSYNCB2/L1GNTB2/TXD1		A22[2]
PB29/L1RSYNCB2/ FCC2_MII_TX_EN/FCC2_RMII_TX_EN	FCC2_UTM_RXCLAV/ FCC2_UTS_RXCLAV	A21[2]
PB30/FCC2_MII_RX_DV/L1RXDB2/ FCC2_RMII_CRS_DV	FCC2_UT_TXSOC	E20[2]
PB31/FCC2_MII_TX_ER/L1TXDB2	FCC2_UT_RXSOC	C20[2]
PC0/DREQ1/BRGO7/$\overline{SMSYN2}$/ L1CLKOA2		AE22[2]
PC1/DREQ2/$\overline{SPISEL}$/BRGO6/$\overline{L1RQA2}$		AA19[2]
PC2/$\overline{FCC3\_CD}$/$\overline{DONE2}$	FCC2_UT8_TXD3	AF24[2]
PC3/$\overline{FCC3\_CTS}$/$\overline{DACK2}$/$\overline{CTS4}$/ USB_RP	FCC2_UT8_TXD2	AE25[2]
PC4/SI2_L1ST4/$\overline{FCC2\_CD}$	$\overline{FCC2\_UTM\_RXENB}$/ FCC2_UTS_RXENB	AB22[2]

Table 25. MPC8275 and MPC8270 (VR and ZQ Packages) Pinout List (continued)

Pin Name		Ball
MPC8275/MPC8270	MPC8275 only	
PD27/TXD2	FCC1_UT16_RXD7	H22[2]
PD28/RXD2	FCC1_UT16_TXD7	B22[2]
PD29/$\overline{RTS1}$/TENA1	FCC1_UTM_RXADDR3/ FCC1_UTS_RXADDR3/ FCC1_UTM_RXCLAV2/ FCC2_UTM_RXADDR4/ FCC2_UTS_RXADDR1	D22[2]
PD30/TXD1	$\overline{FCC2\_UTM\_TXENB}$/ $\overline{FCC2\_UTS\_TXENB}$	C21[2]
PD31/RXD1		E19[2]
VCCSYN		D19
VCCSYN1		K6
CLKIN2		K21
SPARE4[3]		C14
$\overline{PCI\_MODE}$[4]		AD24
SPARE6[3]		B15
No connect[5]		E17, C23
I/O power		E6, F6, H6, L5, L6, P6, T6, U6, V5, Y5, AA6, AA8, AA10, AA11, AA14, AA16, AA17, AB19, AB20, W21, U21, T21, P21, N21, M22, J22, H21, F21, F19, F17, E16, F14, E13, E12, F10, E10, E9
Core Power		L3, V4, W3, AC11, AD11, AB15, U25, T24, J24, H25, F23, B19, D17, C17, D10, C10
Ground		B18[6], A18[7], A2, B1, B2, A5, C5, C18, D4, D6, G2, L4, P1, R1, R4, AC4, AE7, AC23, Y25, N24, J23, A23, D23, D20, E18, A13, A16, K10, K11, K12, K13, K14, K15, K16, K17, L10, L11, L12, L13, L14, L15, L16, L17, M10, M11, M12, M13, M14, M15, M16, M17, N10, N11, N12, N13, N14, N15, N16, N17, P10, P11, P12, P13, P14, P15, P16, P17, R10, R11,R12, R13, R14, R15, R16, R17, T10, T11, T12, T13, T14, T15, T16, T17, U10, U11, U12, U13, U14, U15, U16, U17

[1] Should be tied to VDDH via a 2K Ω external pull-up resistor.

[2] The default configuration of the CPM pins (PA[0–31], PB[4–31], PC[0–31], PD[4–31]) is input. To prevent excessive DC current, it is recommended to either pull unused pins to GND or VDDH, or to configure them as outputs.

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3 Must be pulled down or left floating.

4 If PCI is not desired, must be pulled up or left floating.

5 Sphere is not connected to die.

6 GNDSYN (B18): This pin exists as a separate ground signal in MPC826x(A) devices; it does not exist as a separate ground signal on the MPC8275/MPC8270. New designs must connect B18 to GND and follow the suggestions in Section 4.6, "Layout Practices." Old designs in which the MPC8275/MPC8270 is used as a drop-in replacement can leave the pin connected to GND with the noise filtering capacitors.

7 XFC (A18) pin: This pin is used in MPC826x(A) devices; it is not used in MPC8275/MPC8270 because there is no need for external capacitor to operate the PLL. New designs should connect A18 (XFC) pin to GND. Old designs in which the MPC8275/MPC8270 is used as a drop-in replacement can leave the pin connected to the current capacitor.

9   Package Description

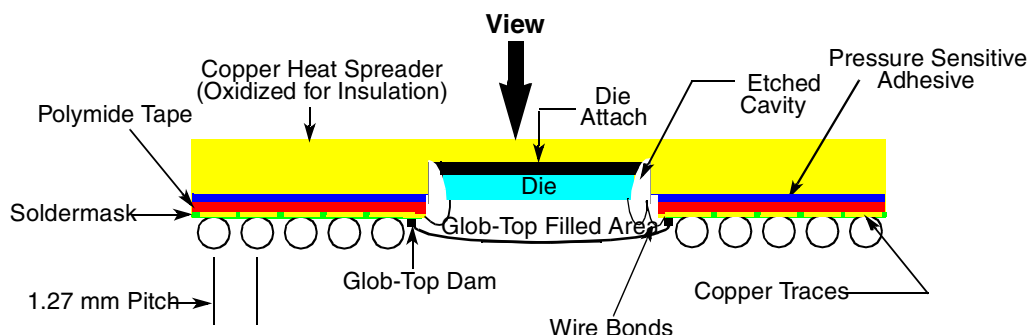This figure shows the side profile of the TBGA package to indicate the direction of the top surface view.

Figure 15. Side View of the TBGA Package

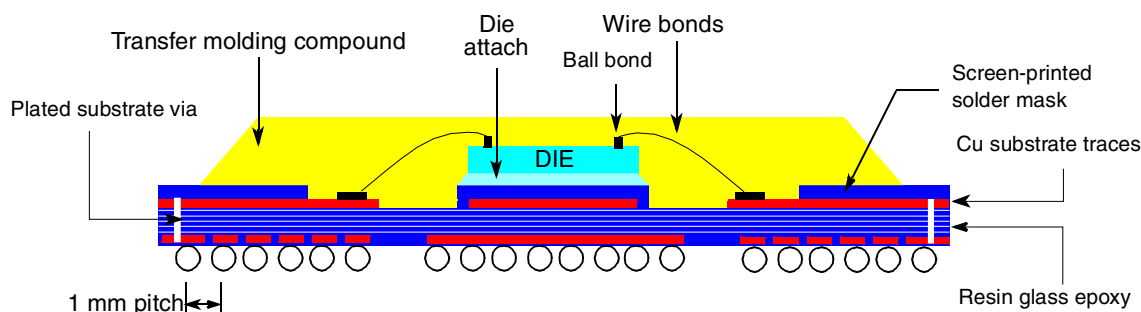This figure shows the side profile of the PBGA package to indicate the direction of the top surface view.

Figure 16. Side View of the PBGA Package Remove